

CLAIMS

We claim:

1. A semiconductor die package, comprising:

a substrate having a first and a second  
5 surface;

a die having a first surface and a second  
surface, wherein the first surface of the die is  
attached to the first surface of the substrate;

10 a heat spreader attached to the second  
surface of the die; and

an encapsulant completely enclosing the die  
and the heat spreader.

2. The die package of Claim 1, wherein the second

15 surface of the die is the face containing active  
circuitry.

3. The die package of Claim 2, wherein the second

15 surface of the die is electrically coupled to the first  
surface of the substrate.

4. The die package of Claim 3, further comprising

bond wires to couple the second surface of the die to  
the first surface of the substrate.

25

5. The die package of Claim 1, further comprising

a conductive ball grid array coupled to the second  
surface of the substrate.

30

6. The die package of Claim 1, further comprising

a thin layer of thermal conductive adhesive between the  
die and the heat slug.

7. The die package of Claim 6, wherein the thin layer is of the order of approximately 1 mil or less.

5 8. The die package of Claim 1, wherein the encapsulant covering the uppermost portion of the heat slug is no more than 9 mils.

9. The die package of Claim 1, wherein the heat 10 slug comprises:

an interior planar portion overlying and attached to the die;

an outer planar portion overlying and attached to at least a portion of the substrate; 15 and

a first angled portion extending from the outer planar portion towards the second surface of the die.

20 10. The die package of Claim 9, wherein the outer planar portion only overlies portions of the substrate in a direction extending laterally from the four sides of the die.

25 11. The die package of Claim 9, wherein the outer planar portion overlies substantially all of the outer portions of the substrate.

30 12. The die package of Claim 1, wherein the first surface of the die is the face containing active circuitry.

13. The die package of Claim 12, wherein the first surface of the die is electrically coupled to the first surface of the substrate.

5 14. The die package of Claim 13, further comprising an array of solder bumps to couple the first surface of the die to the first surface of the substrate.

10 15. The die package of Claim 9, wherein a thin layer of encapsulant is located between the outer planar portion of the heat slug and the first surface of the substrate.

15 16. A ball grid array (BGA) package, comprising:  
a substrate;  
a die coupled to the substrate;  
a thin thermal conductive adhesive layer on the die;  
20 a heat slug attached to the die with the adhesive layer; and  
an encapsulant completely covering the heat slug.

25 17. The BGA package of Claim 16 wherein the encapsulant covering the uppermost portion of the heat slug is no more than 9 mils.

30 18. The BGA package of Claim 16, wherein the heat slug comprises:  
an interior planar portion overlying and attached to the die;

an outer planar portion overlying and attached to at least a portion of the substrate; and

5 a first angled portion extending from the outer planar portion towards the upper surface of the die.

19. The BGA package of Claim 18, wherein a thin layer of encapsulant is located between the outer 10 planar portion of the heat slug and the upper surface of the substrate.

20. A method of dissipating heat from a ball grid array package, comprising:

15 attaching a die to a substrate;

attaching a heat slug directly to the die;

and

20 encapsulating the die and the heat spreader completely.

21. The method of Claim 20, further comprising leaving a thin layer of encapsulant over the upper most portion of the heat slug.

25 22. The method of Claim 20, further comprising forming a thin layer of encapsulant between the outer portion of heat slug and the upper surface of the substrate.

30 23. A method of packaging a semiconductor die, comprising:

providing a substrate;

attaching a first surface of the die to the substrate;

attaching a heat slug directly to a second surface of the die, the second surface opposing the first surface; and

5 completely covering the heat slug with an encapsulant.